BGA Heat Sink - High Performance maxiFLOW/superGRIP





ATS Part#: ATS-X50300P-C1-R0

Description: 30.00 x 30.00 x 17.50 mm BGA Heat Sink - High

Performance maxiFLOW/superGRIP

Heat Sink Type: maxiFLOW
Heat Sink Attachment: superGRIP

Equivalent Part Number: N/A

*Image above is for illustration purpose only.

Features & Benefits

- Designed for 30 x 30 mm components
- · Requires minimal space around the component's perimeter; ideal for densely populated PCBs
- Allows the heat sink to be detached and reattached without damaging the component or the PCB, an important feature in the event a PCB may need to be reworked
- Strong, uniform attachment force helps achieve maximum performance from phase-changing TIMs
- Eliminates the need to drill mounting holes in the PCB

Thermal Performance

AIR VELOCITY		@200 LFM 1.0 M/S	@300 LFM 1.5 M/S	@400 LFM 2.0 M/S	@500 LFM 2.5 M/S	@600 LFM 3.0 M/S	@700 LFM 3.5 M/S	@800 LFM 4.0 M/S
THERMAL RESISTANCE	Unducted Flow	3.4 °C/W	2.8 °C/W	2.4 °C/W	2.2 °C/W	2 °C/W	1.9 °C/W	1.7 °C/W
	Ducted Flow	2.7	N/A	N/A	N/A	N/A	N/A	N/A

Product Detail

Schematic Image	Dimension A	Dimension B	Dimension C	Dimension D	ТІМ	Finish
	30.00 mm	30.00 mm	17.50 mm	53.3 mm	T766	BLUE-ANODIZED
*Image above is for illustration purpose only.	 Dimension Thermal papplication ATS reserperforman ATS certifities 	performance data are no. The right to update once. The right heat single that this heat single performance.	emponent size. The provided for reference are or change its provided k assembly is RoHS astom options available.	nce only. Actual performance only. Actual performance ducts without notice	ormance to improv	may vary by



